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U.S. DEPARTMENT OF COMMERCE
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Attorney Docket No. 501.44460X00

To the Honorable Commissioner of Patent

102913957

Mail documents or copy thereof.

1. Name of conveying party(ies):
UJIIE, KENJI
KURATOMI, BUNSHI

2. Name and address of receiving party(ies)
Name: **RENESAS TECHNOLOGY CORP.**

Street Address:

4-1, Marunouchi 2-chome,
Chiyoda-ku,
Tokyo, JAPAN

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other .

Execution Date: **Oct. 19, 2004.**

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: **Oct. 19, 2004.**

A. Patent Application No.(s)

B. Patent Registration No.(s)

Additional number(s) attached ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **ANTONELLI, TERRY, STOUT & KRAUS, LLP**

Internal Address:

1300 NORTH 17TH STREET - SUITE 1800

City: **ARLINGTON** State: **VA** Zip **22209**

6. Total number of applications and patents involved **1**

7. Total fee (37 CFR 3.41)..... **\$40.00**

☒ Enclosed

☒ Authorized to be charged to deposit account

8. Deposit account number:

01-2135

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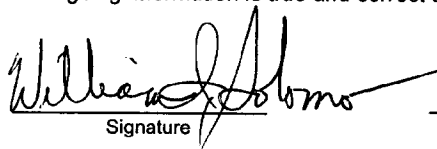
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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

WILLIAM I. SOLOMON, Reg #28,565

Name of Person Signing


Signature

12/16/2004

Date

Total number of pages including cover sheet, attachments, and document: **2**

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PATENT
REEL: 016103 FRAME: 0617

ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp., a corporation organized under the laws of Japan, located at 4-1, Marunouchi 2-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

A MANUFACTURING METHOD OF A SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Renesas Technology Corp., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1)	<i>Kenji Ujiie</i> Kenji UJIE	<i>19 / Oct. / 2004</i>
2)	<i>Bunshi Kuratomi</i> Bunji KURATOMI	<i>19 / Oct. / 2004</i>
3)		
4)		
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